

# Characterization and fabrication of monolayer graphene on h-BN semiconducting devices

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Since first isolated in 2004, graphene has established itself as a promising material in semi-conducting devices, exhibiting a host of unique properties regarding collective electron behavior.<sup>1</sup> With respect to electronic applications, graphene's massless charge carriers, referred to as Dirac fermions and exhibiting a relativistic-like energy dispersion, offer the potential to push semiconductor technology past the usage of silicon, whose mobility is far exceeded by that of graphene.<sup>2</sup> However, because this high mobility is primarily observed only in isolated settings, one of the objectives for graphene researchers in electronics has been to create and perfect more-practical graphene field effect devices (FEDs). While retaining ultra-fast carrier mobility is difficult, mobility in graphene FEDs still exceeds that in traditional silicon devices.<sup>3</sup> Since traditional FEDs are typically fabricated on silicon/silicon-dioxide wafers, recent discovery of hexagonal boron-nitride (*h*-BN), a material with only a 1.7% lattice mismatch with graphite, has increased hope of reaching isolated graphene level mobility.<sup>4</sup> Motivated by this, we have used a methodology involving monolayer graphene preparation by mechanical exfoliation and transfer to *h*-BN via PMMA. Characteristic data has been taken at low-temperature using liquid He.

<sup>1</sup> K. S. Novoselov, *et al.*, Science **306**, 666 (2004).

<sup>2</sup> K. S. Novoselov, *et al.*, Nature **438**, 197 (2005).

<sup>3</sup> M. C. Lemme, *et. al.*, IEEE Electron Device Lett. **28**, 4 (2007).

<sup>4</sup> C. R. Dean, *et. al.*, Nature Nanotech. **5**, 722 (2010).



# CHARACTERIZATION AND FABRICATION OF MONOLAYER GRAPHENE ON H-BN SEMICONDUCTING DEVICES

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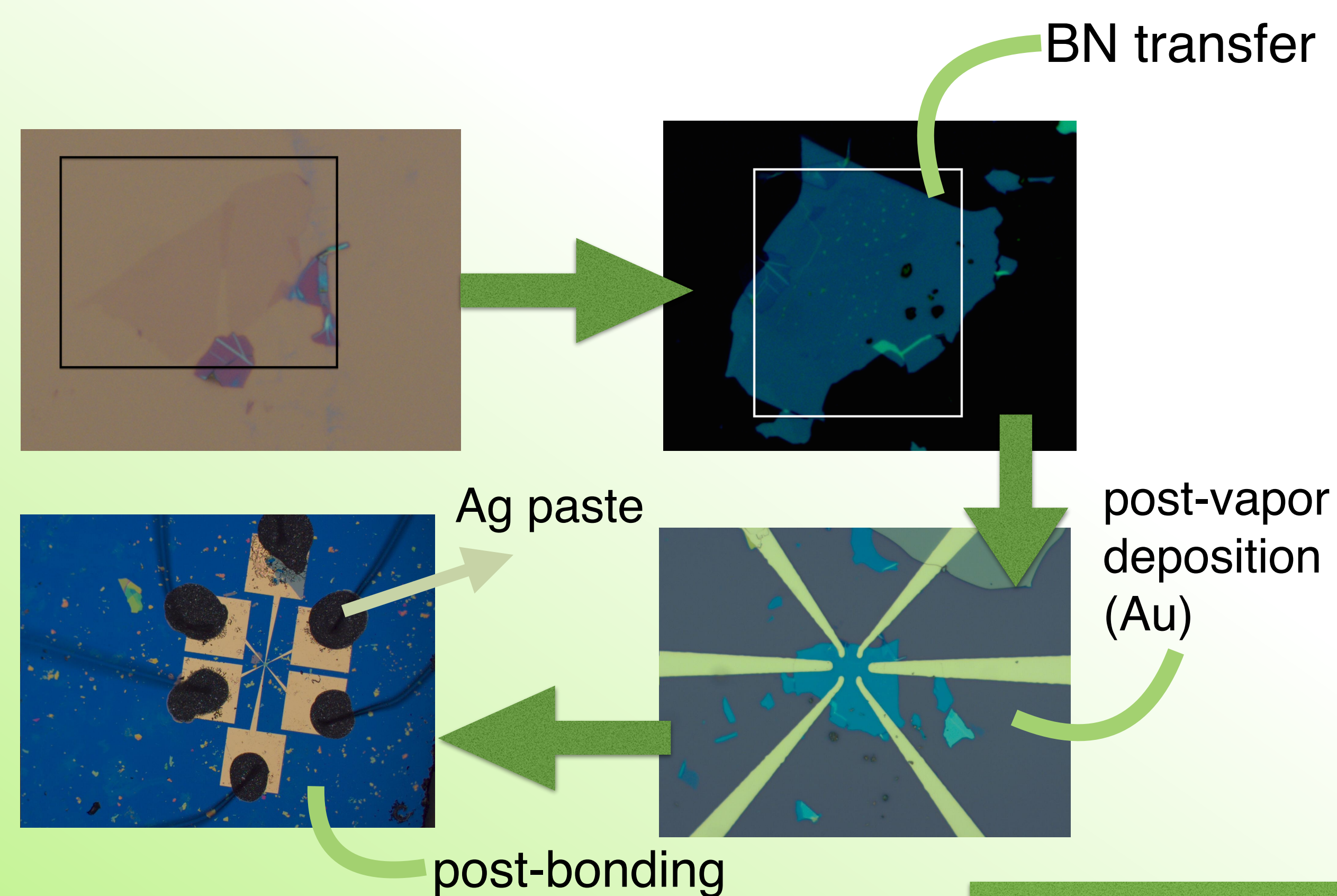
千葉大学  
Chiba University

## Introduction

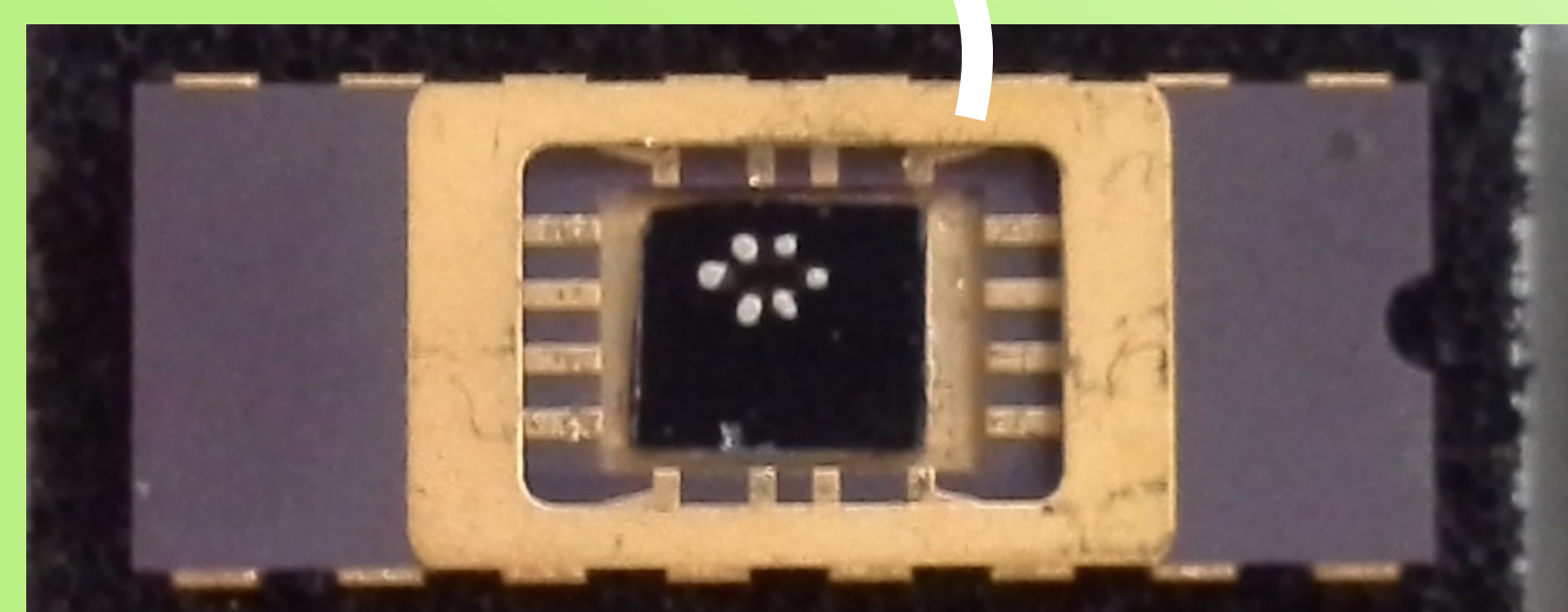
**Objective:** Characterize a monolayer graphene hexagonal boron-nitride device with high mobility at low-temperature

## Method

1. Preparation of graphene by micro-mechanical exfoliation (Si surface), PVA/PMMA coating
2. Preparation of BN on SiO<sub>2</sub>
3. Transfer via floating PMMA

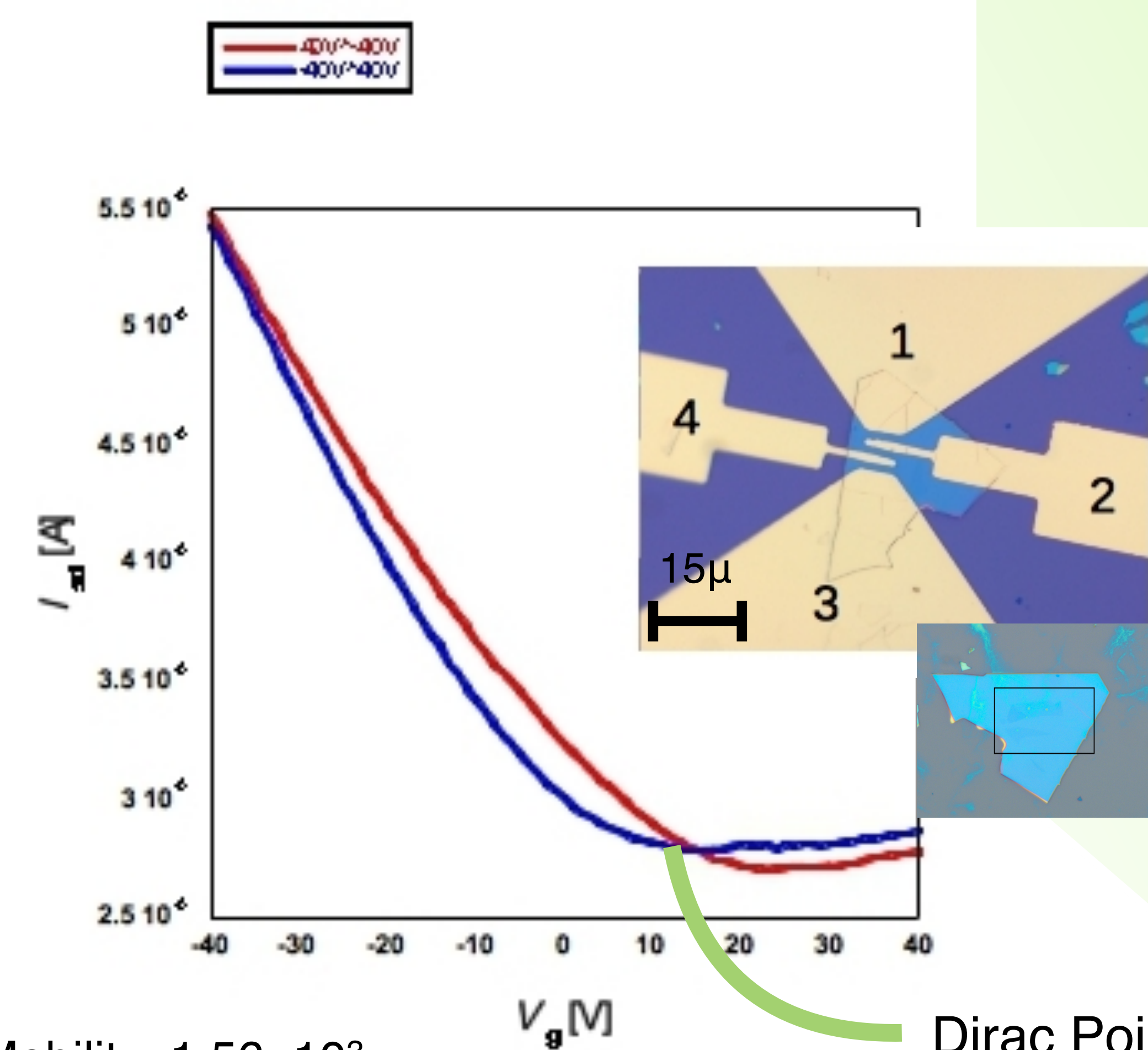


4. Removal of PMMA and addition of photo resist (LOR, V90)
5. Photolithography
6. Vapor deposition (Au, Sn) and liftoff (NMD-3)
7. Bonding (to chip carrier) and low-temperature preparation



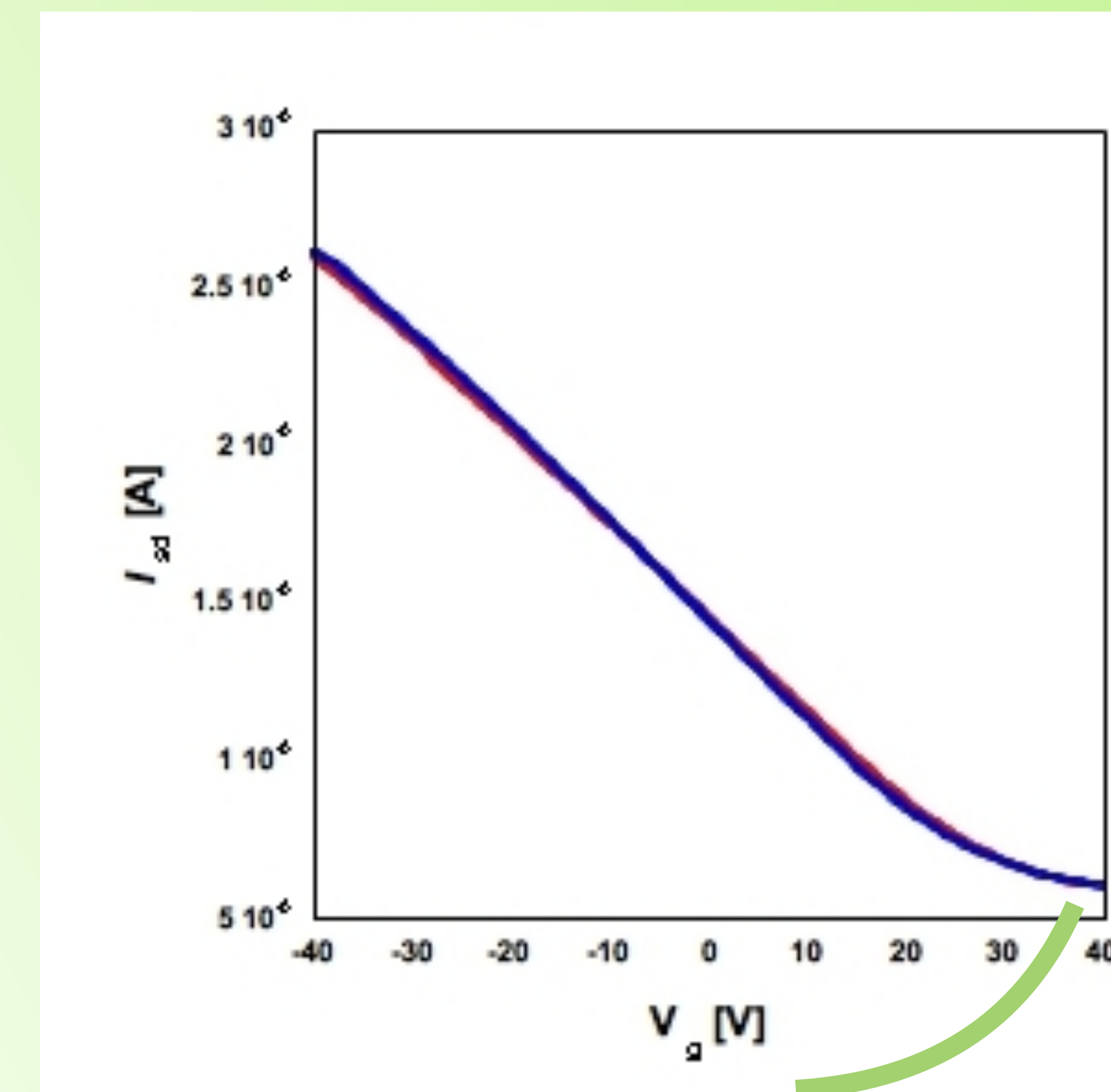
## Results & Discussion

### Sample Properties



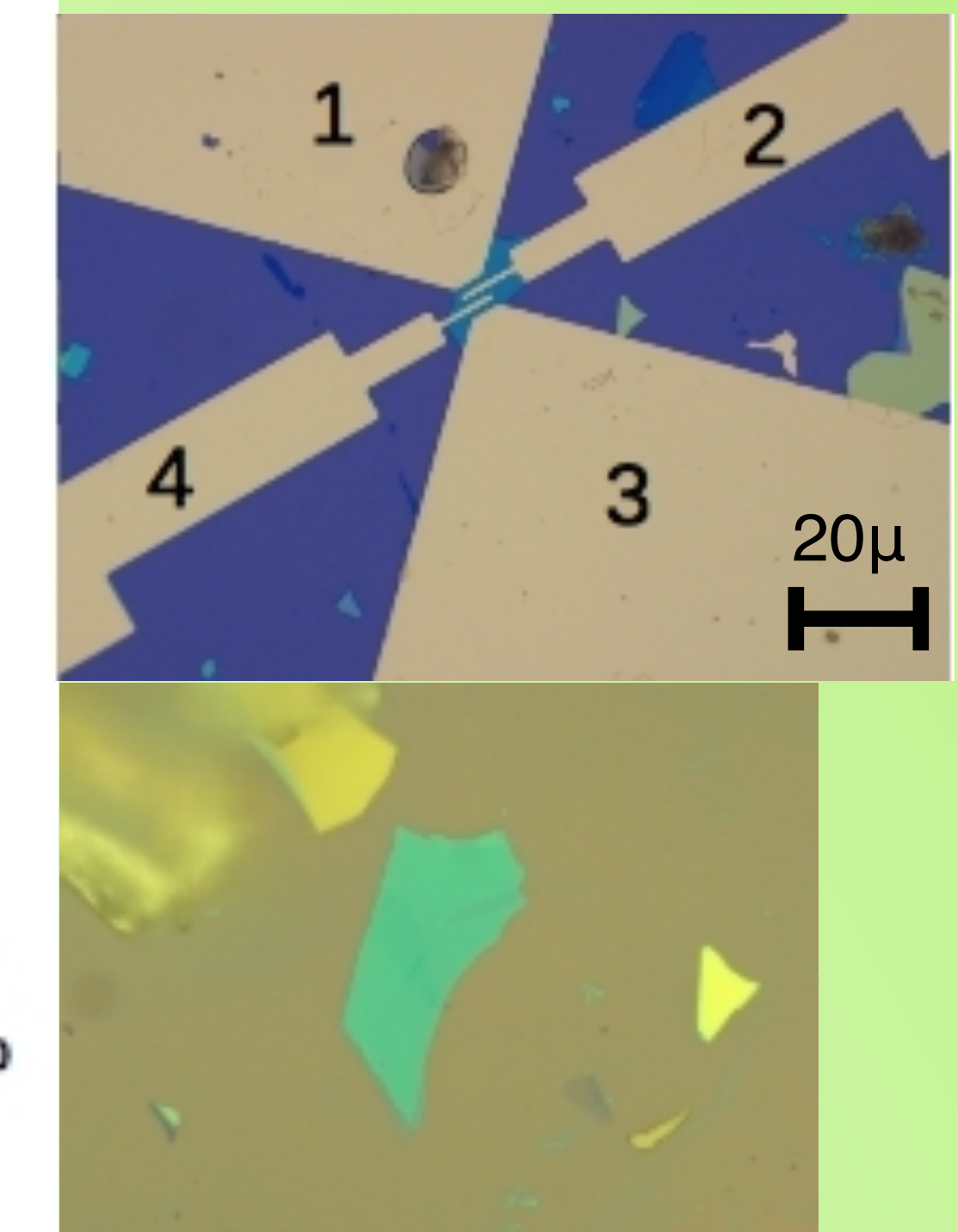
Mobility:  $1.56 \times 10^3$  [cm<sup>2</sup>/Vs]  
Carrier density ( $n_e$ ):  $2.25 \times 10^{11}$  [/cm<sup>2</sup>]

Dirac Point (~10 V),  
 $V_g$  step: 1 V



Dirac Point (~-40 V),  
 $V_g$  step: 1 V

Mobility:  $2.22 \times 10^3$  [cm<sup>2</sup>/Vs]  
Carrier density ( $n_e$ ):  $6.91 \times 10^{11}$  [/cm<sup>2</sup>]

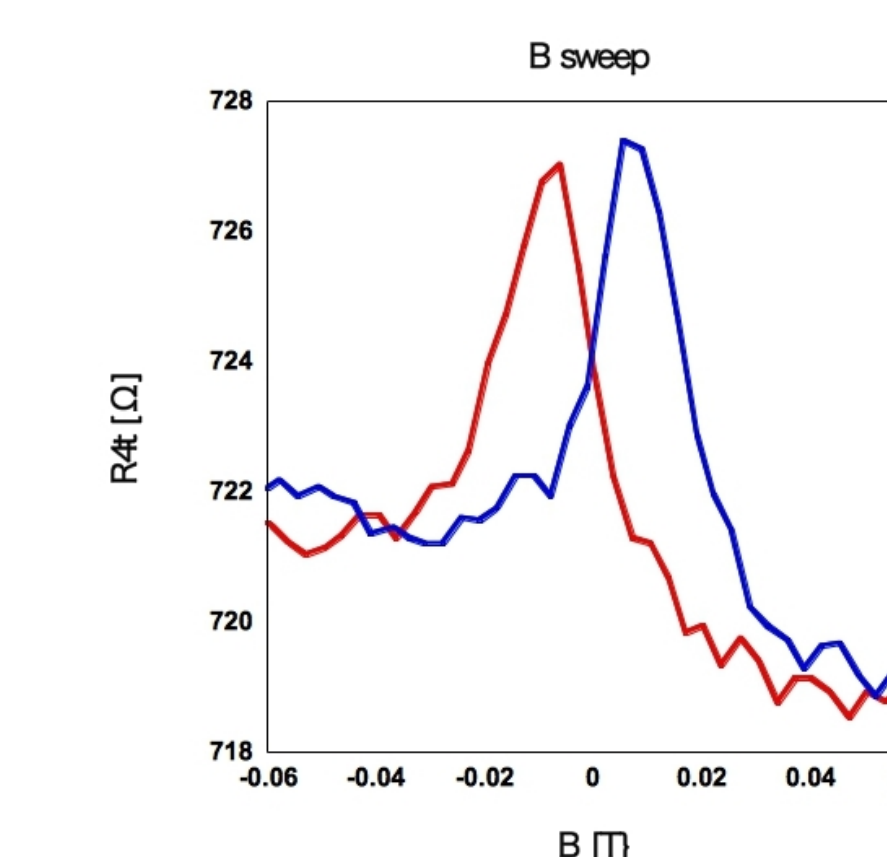
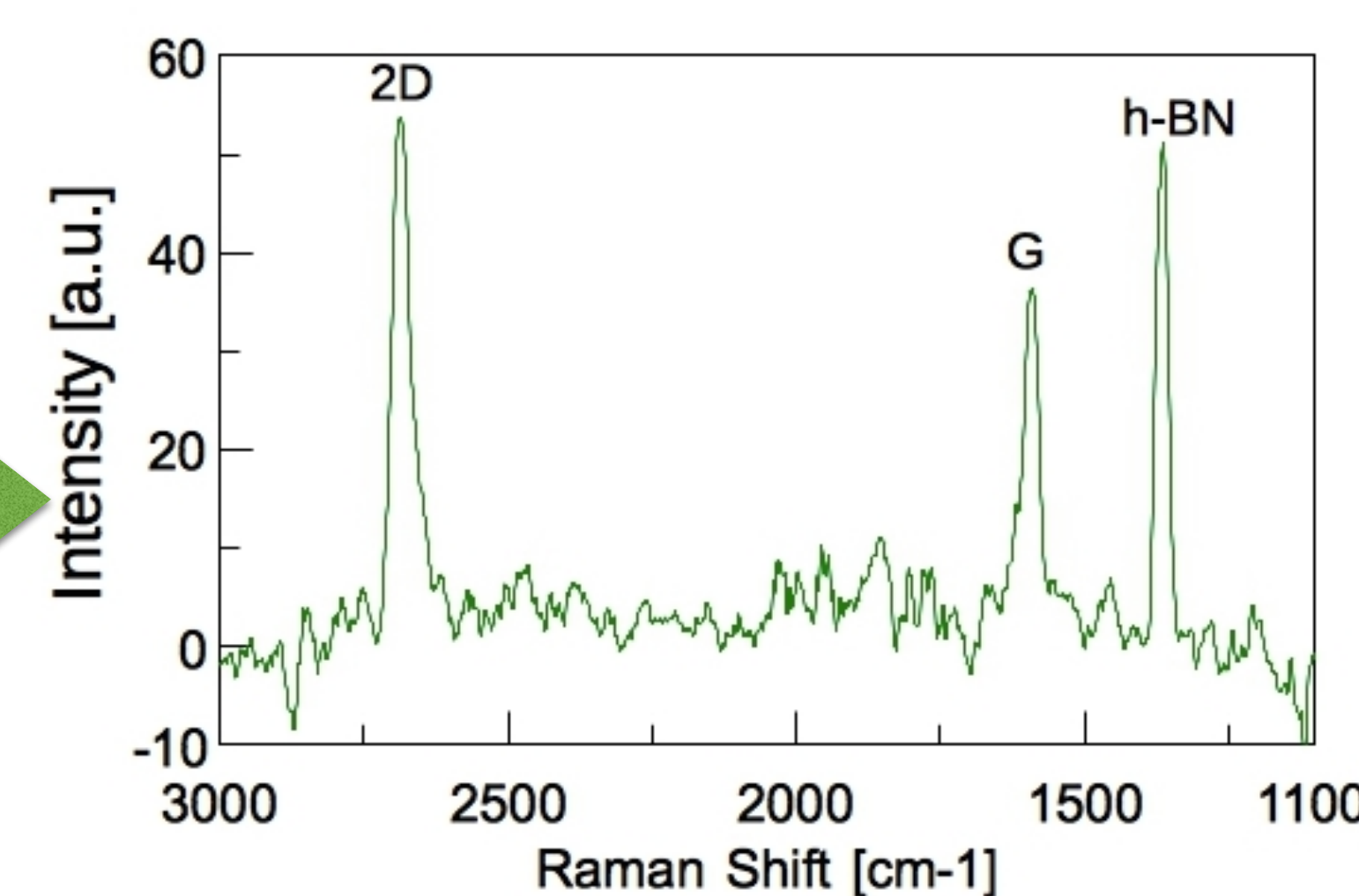


### Summary

This was the lab's first experiment involving graphene on BN as opposed to just SiO<sub>2</sub>. We hope that the usage of BN, a flat, hydrophobic surface (no dangling bonds) high band gap insulator, will lead to devices with higher mobility than the traditional graphene-SiO<sub>2</sub> device.

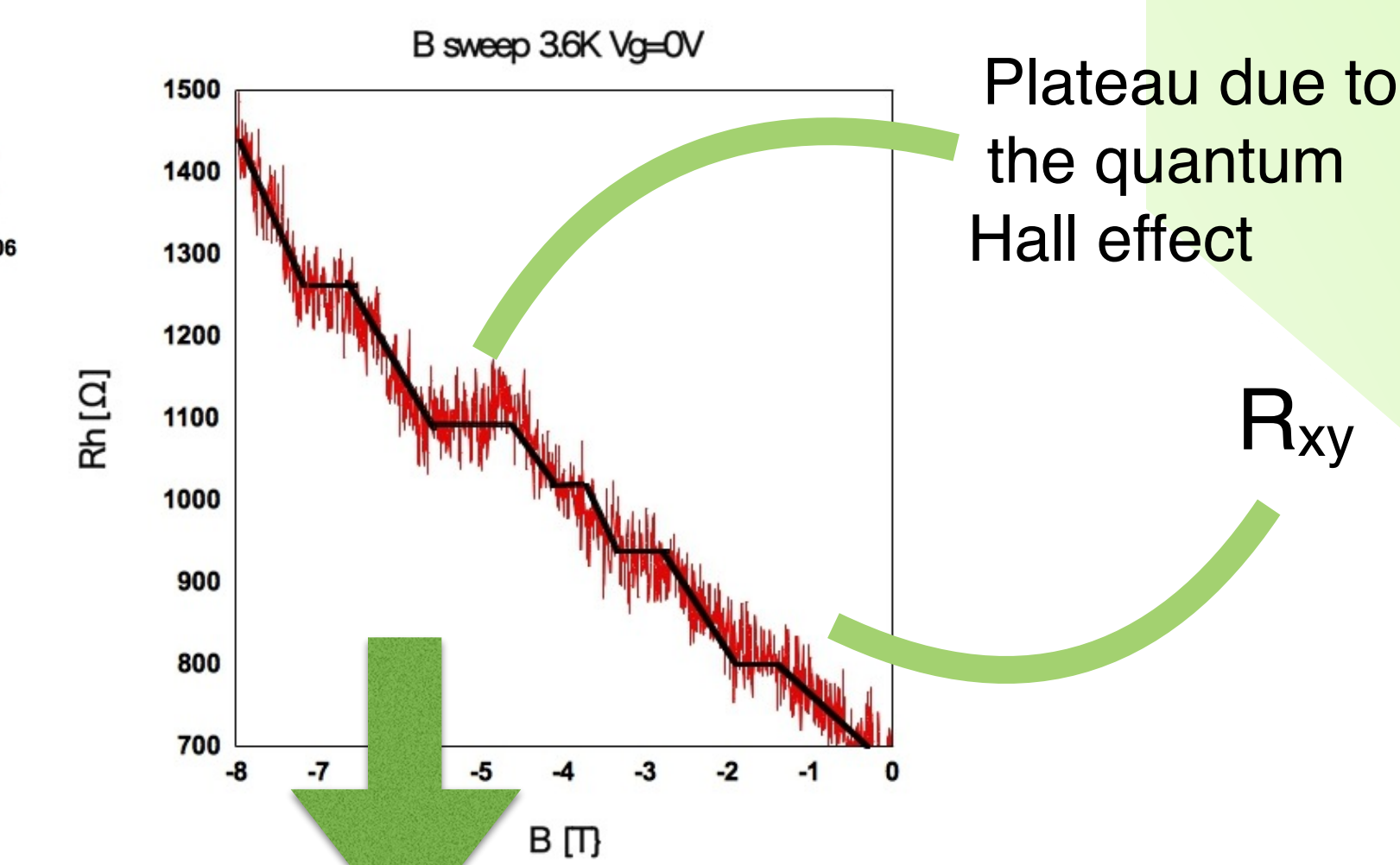
### Low-Temperature

#### Raman Spectroscopy



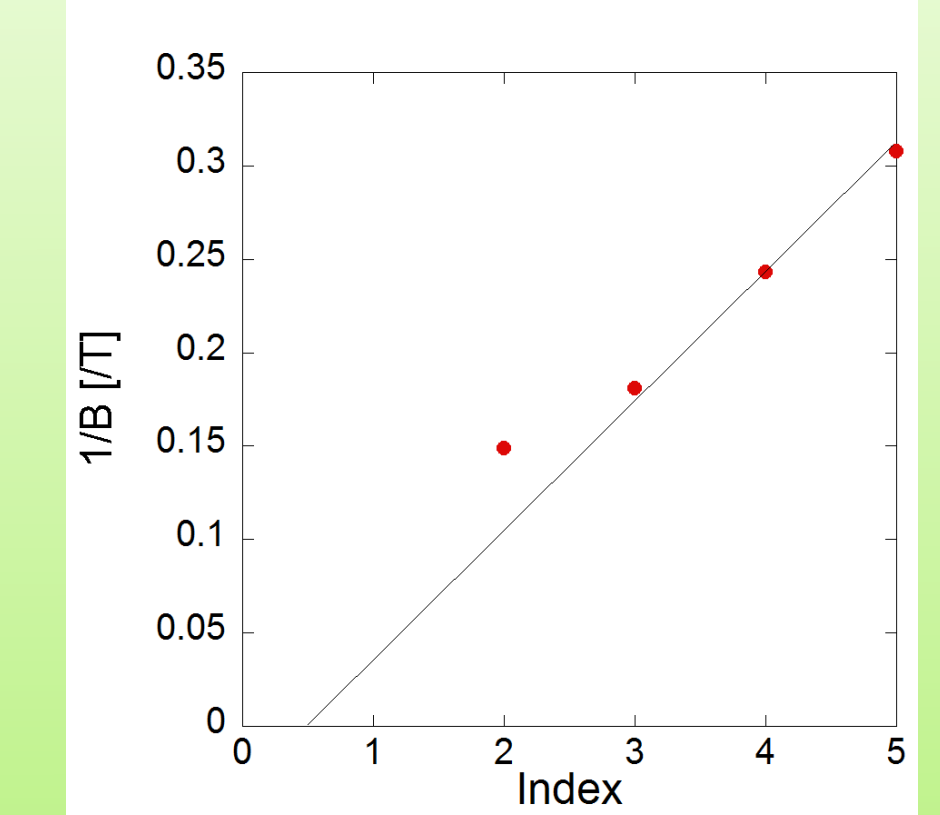
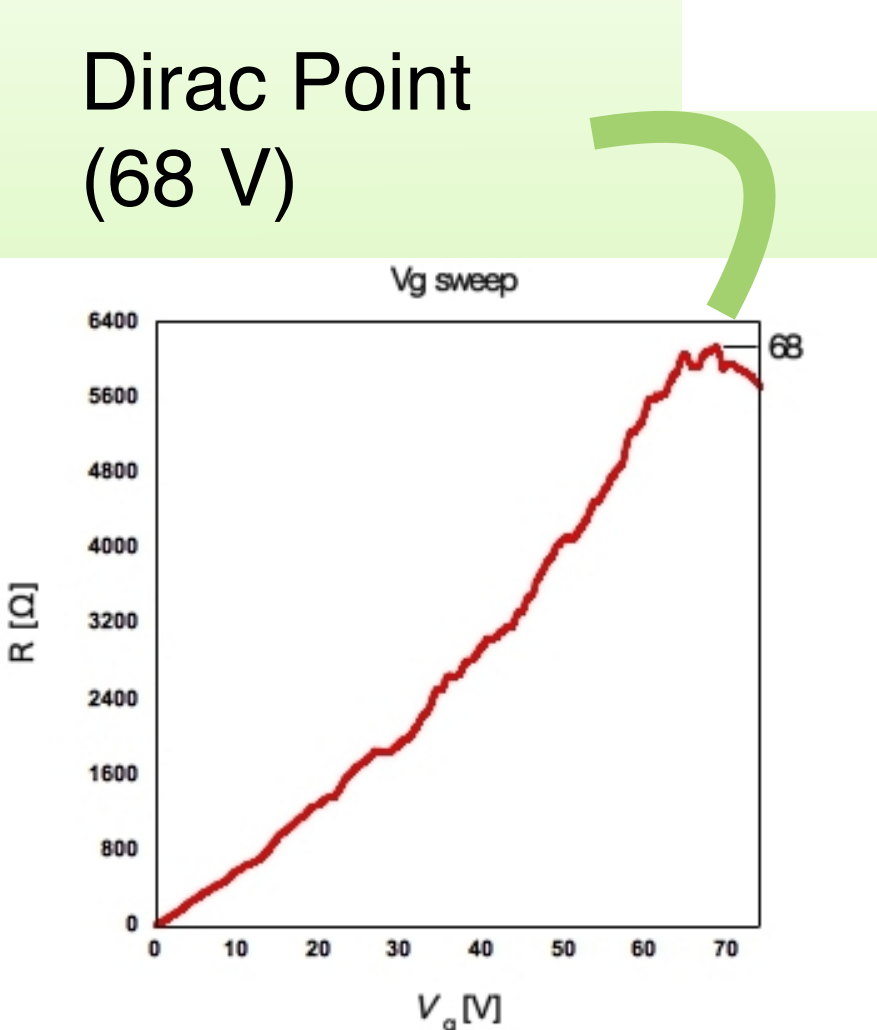
According to Raman, the sample is monolayer.

#### Magnetic Resistance



#### Characteristics

$n_e = 1/e(dR_{xy}/dB)$   
 $\mu = (L/W)(en_e R_{xx})^{-1}$   
 $B_c S_\phi = h/e$   
**Low-Temperature Properties**  
 $B_c = 0.017$  [T]  
 $L_\phi = 493$ ,  $L = 9$  [μm],  $W = 6$  [μm]  
 $n_e = 2.96 \times 10^{12}$  [/cm<sup>2</sup>]  
 $\mu = 4.36 \times 10^3$  [cm<sup>2</sup>/Vs]



#### Acknowledgements

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